



## Outline

- -Fully-automatic LC Tape laminator which laminates Adwill LC Tape to wafer backside after back grinding.
- -Performs the following functions:
- · Wafer alignment
- · LC Tape pre-cutting
- · LC Tape lamanation
- · Release liner peeling

- Options · Host Communication Function (Communication Format :
  - Conforms to SECS-I and HSMS/Software: Conforms to GEM)
  - ·Double Cassette Loading
  - ·Wafer ID Reader
- Suitable Tape · Backside coating tape : Adwill LC Tape

### Facility

Voltage **Power Supply** : AC200-230V ±10%

(AC190-253V)

Frequency : 50/60Hz Phase : single phase Power consumption : 6.0kW : 0.5-0.8MPa

**Air Supply** Air pressure

: >150L/min (ANR) Air consumption

**Vacuum Supply** Vacuum pressure :>-80kPa

Applicable Wafer Size 200mm, 300mm

Width: 1,550mm Size

Depth: 1,950mm Height: 1,800mm

(excluding the signal tower and protruding parts)

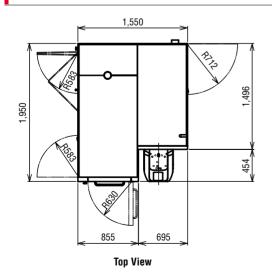
Weight 1,500kg

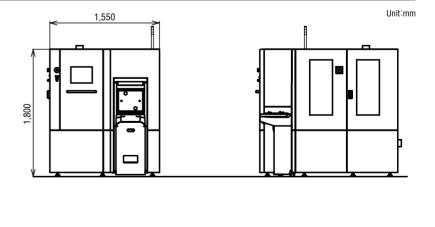
UPH 30 wafers/hour (excludes setting time)

The above processing capacity is based on following conditions: : 300mm diameter non-polished mirror wafer Wafer

LC Tape : LC2850(40) from LINTEC

# External View





**Front View Right Side View** 

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